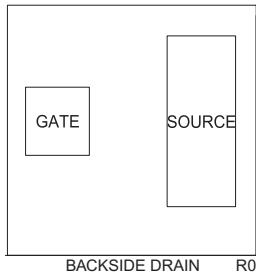


The CP324X-2N7002 is a silicon N-Channel MOSFET designed for high speed pulsed amplifier and driver applications.



**MECHANICAL SPECIFICATIONS:**

|                         |                    |  |
|-------------------------|--------------------|--|
| Die Size                | 21.65 x 21.65 MILS |  |
| Die Thickness           | 5.9 MILS           |  |
| Gate Bonding Pad Size   | 5.5 x 5.5 MILS     |  |
| Source Bonding Pad Size | 5.9 x 13.8MILS     |  |
| Top Side Metalization   | Al – 30,000Å       |  |
| Back Side Metalization  | Au – 12,000Å       |  |
| Scribe Alley Width      | 1.97 MILS          |  |
| Wafer Diameter          | 6 INCHES           |  |
| Gross Die Per Wafer     | 48,613             |  |

**MAXIMUM RATINGS:** ( $T_A=25^\circ\text{C}$ )

|  | <b>SYMBOL</b>  |             | <b>UNITS</b>     |
|--|----------------|-------------|------------------|
| Drain-Source Voltage                       | $V_{DS}$       | 60          | V                |
| Drain-Gate Voltage                         | $V_{DG}$       | 60          | V                |
| Gate-Source Voltage                        | $V_{GS}$       | 40          | V                |
| Continuous Drain Current                   | $I_D$          | 115         | mA               |
| Continuous Source Current (Body Diode)     | $I_S$          | 115         | mA               |
| Maximum Pulsed Drain Current               | $I_{DM}$       | 800         | mA               |
| Maximum Pulsed Source Current              | $I_{SM}$       | 800         | mA               |
| Operating and Storage Junction Temperature | $T_J, T_{stg}$ | -65 to +150 | $^\circ\text{C}$ |

**ELECTRICAL CHARACTERISTICS:** ( $T_A=25^\circ\text{C}$  unless otherwise noted)

| <b>SYMBOL</b>        | <b>TEST CONDITIONS</b>                         | <b>MIN</b> | <b>MAX</b> | <b>UNITS</b>  |
|----------------------|--|------------|------------|---------------|
| $I_{GSSF}, I_{GSSR}$ | $V_{GS}=20\text{V}, V_{DS}=0$                  |            | 100        | nA            |
| $I_{DSS}$            | $V_{DS}=60\text{V}, V_{GS}=0$                  |            | 1.0        | $\mu\text{A}$ |
| $I_{D(ON)}$          | $V_{GS}=10\text{V}, V_{DS}=10\text{V}$         | 500        |            | mA            |
| $BV_{DSS}$           | $V_{GS}=0, I_D=10\mu\text{A}$                  | 60         |            | V             |
| $V_{GS(th)}$         | $V_{DS}=V_{GS}, I_D=250\mu\text{A}$            | 1.0        | 2.5        | V             |
| $V_{DS(ON)}$         | $V_{GS}=10\text{V}, I_D=500\text{mA}$          |            | 3.75       | V             |
| $V_{DS(ON)}$         | $V_{GS}=5.0\text{V}, I_D=50\text{mA}$          |            | 0.375      | V             |
| $V_{SD}$             | $V_{GS}=0, I_S=11.5\text{mA}$                  |            | 1.5        | V             |
| $r_{DS(ON)}$         | $V_{GS}=10\text{V}, I_D=500\text{mA}$          |            | 7.5        | $\Omega$      |
| $r_{DS(ON)}$         | $V_{GS}=5.0\text{V}, I_D=50\text{mA}$          |            | 7.5        | $\Omega$      |
| $g_{FS}$             | $V_{DS} = 10\text{V}, I_D=200\text{mA}$        | 80         |            | $\text{mS}$   |
| $C_{rss}$            | $V_{DS}=25\text{V}, V_{GS}=0, f=1.0\text{MHz}$ |            | 5.0        | pF            |
| $C_{iss}$            | $V_{DS}=25\text{V}, V_{GS}=0, f=1.0\text{MHz}$ |            | 50         | pF            |
| $C_{oss}$            | $V_{DS}=25\text{V}, V_{GS}=0, f=1.0\text{MHz}$ |            | 25         | pF            |

# **CP324X-2N7002**

## **N-Channel MOSFET Die**

### **Enhancement-Mode**



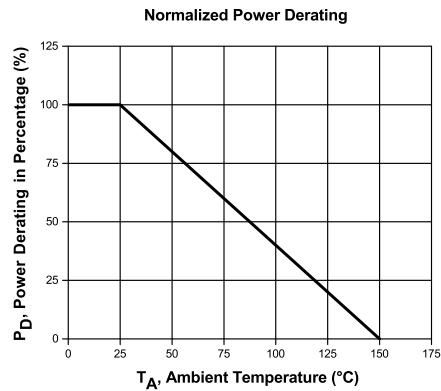
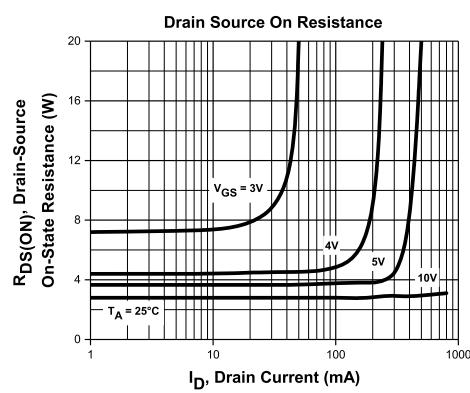
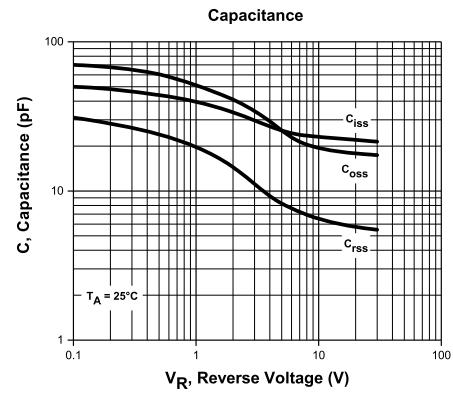
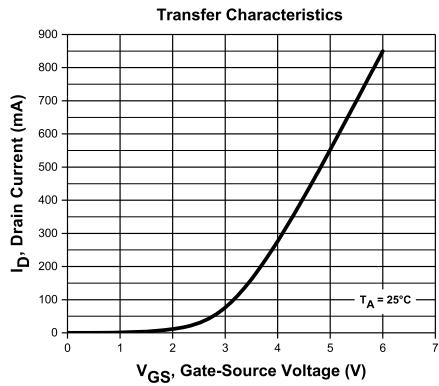
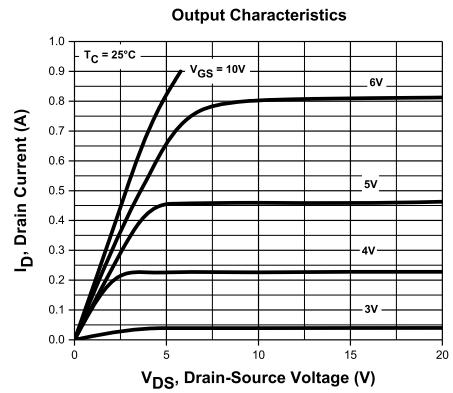
[www.centralsemi.com](http://www.centralsemi.com)

**ELECTRICAL CHARACTERISTICS** - Continued: ( $T_A=25^\circ C$  unless otherwise noted)

| SYMBOL            | TEST CONDITIONS                                      | TYP   | MAX | UNITS |
|-------------------|--|-------|-----|-------|
| $Q_g(\text{tot})$ | $V_{DS}=30V, V_{GS}=4.5V, I_D=100mA$                 | 0.592 |     | nC    |
| $Q_{gs}$          | $V_{DS}=30V, V_{GS}=4.5V, I_D=100mA$                 | 0.196 |     | nC    |
| $Q_{gd}$          | $V_{DS}=30V, V_{GS}=4.5V, I_D=100mA$                 | 0.148 |     | nC    |
| $t_{on}$          | $V_{DD}=30V, I_D=200mA, R_G=25\Omega, R_L=150\Omega$ |       | 20  | ns    |
| $t_{off}$         | $V_{DD}=30V, I_D=200mA, R_G=25\Omega, R_L=150\Omega$ |       | 20  | ns    |

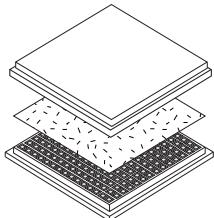
# CP324X-2N7002

## Typical Electrical Characteristics



## BARE DIE PACKING OPTIONS

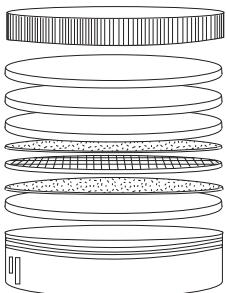
---



### BARE DIE IN TRAY (WAFFLE) PACK

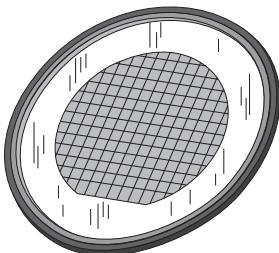
**CT:** Singulated die in tray (waffle) pack.  
(example: CP211-PART NUMBER-CT)

**CM:** Singulated die in tray (waffle) pack 100% visually inspected as per MIL-STD-750, (method 2072 transistors, method 2073 diodes).  
(example: CP211-PART NUMBER-CM)



### UNSAWN WAFER

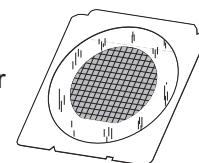
**WN:** Full wafer, unsawn, 100% tested with reject die inked.  
(example: CP211-PART NUMBER-WN)



### SAWN WAFER ON PLASTIC RING

**WR:** Full wafer, sawn and mounted on plastic ring,  
100% tested with reject die inked.  
(example: CP211-PART NUMBER-WR)

Please note: Sawn Wafer on Metal Frame (WS)  
is possible as a special order. Please contact your  
Central Sales Representative at 631-435-1110.



R1 (10-February 2017)

## OUTSTANDING SUPPORT AND SUPERIOR SERVICES



---

### PRODUCT SUPPORT

Central's operations team provides the highest level of support to insure product is delivered on-time.

- Supply management (Customer portals)
- Inventory bonding
- Consolidated shipping options
- Custom bar coding for shipments
- Custom product packing

---

### DESIGNER SUPPORT/SERVICES

Central's applications engineering team is ready to discuss your design challenges. Just ask.

- Free quick ship samples (2<sup>nd</sup> day air)
- Online technical data and parametric search
- SPICE models
- Custom electrical curves
- Environmental regulation compliance
- Customer specific screening
- Up-screening capabilities
- Special wafer diffusions
- PbSn plating options
- Package details
- Application notes
- Application and design sample kits
- Custom product and package development

---

### CONTACT US

#### Corporate Headquarters & Customer Support Team

Central Semiconductor Corp.  
145 Adams Avenue  
Hauppauge, NY 11788 USA  
Main Tel: (631) 435-1110  
Main Fax: (631) 435-1824  
Support Team Fax: (631) 435-3388  
[www.centralsemi.com](http://www.centralsemi.com)

**Worldwide Field Representatives:**  
[www.centralsemi.com/wwreps](http://www.centralsemi.com/wwreps)

**Worldwide Distributors:**  
[www.centralsemi.com/wwdistributors](http://www.centralsemi.com/wwdistributors)

---

For the latest version of Central Semiconductor's **LIMITATIONS AND DAMAGES DISCLAIMER**, which is part of Central's Standard Terms and Conditions of sale, visit: [www.centralsemi.com/terms](http://www.centralsemi.com/terms)